

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	6	(shao-yu near2 ting) or (shih-feng near2 chen) or (wei-pin near2 jao) or (shou-chi near2 tseng) or (yuan-chih near2 hsieh)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/14 12:58
S3	2728	(winbond adj electronics).as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/14 12:55
S4	7	S3 and (electroplating or plating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/14 12:56
S5	0	09/105207	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/14 12:58
S6	1	"105207".apn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/14 13:00
S9	2114	("204" "205").clas. and electroplating and ((flow adj distribut\$4) or diffus\$4)	US-PGPUB; USPAT	OR	ON	2005/10/14 13:08
S10	39	S9 and funnel	US-PGPUB; USPAT	OR	ON	2005/10/14 13:02
S12	1807	S9 and (semiconductor or wafer or substrate or workpiece)	US-PGPUB; USPAT	OR	ON	2005/10/14 15:17
S14	186	S12 and anode with (mesh\$3 or perforat\$4)	US-PGPUB; USPAT	OR	ON	2005/10/14 17:04
S15	62	S14 and overflow\$4	US-PGPUB; USPAT	OR	ON	2005/10/14 13:10
S16	410	S12 and anode and inner and outer	US-PGPUB; USPAT	OR	ON	2005/10/14 17:05
S18	339	S16 not S14	US-PGPUB; USPAT	OR	ON	2005/10/14 15:18
S19	5535	(204/224R.ccls.) or (204/212,287, 237,283,284,263).ccls. or (205/96,101,125,148,157).ccls.	US-PGPUB; USPAT	OR	ON	2005/10/14 15:16

S20	1773	S19 and (electroplating or (electrochemical adj plating))	US-PGPUB; USPAT	OR	ON	2005/10/14 15:16
S21	1299	S20 and (semiconductor or wafer or substrate or workpiece)	US-PGPUB; USPAT	OR	ON	2005/10/14 15:17
S22	443	S21 and (fluid adj distribut\$4 or diffus\$4)	US-PGPUB; USPAT	OR	ON	2005/10/14 15:19
S23	295	S22 not S16	US-PGPUB; USPAT	OR	ON	2005/10/14 15:19
S24	16	(US-20030057098-\$ or US-20030089608-\$ or US-20030178297-\$ or US-20030217916-\$ or US-20020053509-\$ or US-20010050233-\$).did. or (US-5514258-\$ or US-6176995-\$ or US-6254742-\$ or US-6413403-\$ or US-6773571-\$ or US-6261426-\$ or US-4466864-\$ or US-6231743-\$ or US-6500324-\$ or US-6174425-\$).did.	US-PGPUB; USPAT	OR	ON	2005/10/14 17:29
S25	11	S24 and mm	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/14 17:33
S27	51	S12 and anode near2 (mesh or perforat\$4)	US-PGPUB; USPAT	OR	ON	2005/10/14 17:04
S28	256	S12 and (anode or counterelectrode or electrode) with (mesh\$3 or perforat\$4)	US-PGPUB; USPAT	OR	ON	2005/10/14 17:05
S29	90	S12 and (anode or counterelectrode or electrode) near2 (mesh\$3 or perforat\$4)	US-PGPUB; USPAT	OR	ON	2005/10/14 17:09
S31	26	S29 and inner and outer	US-PGPUB; USPAT	OR	ON	2005/10/14 17:05
S32	2	S24 and ((non adj conductive) or dielectric or insulat\$4) with diffuser	US-PGPUB; USPAT	OR	ON	2005/10/14 17:41
S33	3	S24 and anode near2 (mesh\$3 or perforat\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/14 17:36
S34	1	((non adj conductive) or dielectric or insulat\$4) near5 diffuser and (anode or (counter adj electrode) or counterelectrode) near2 (mesh\$3 or perforat\$4)	US-PGPUB; USPAT	OR	ON	2005/10/14 17:43

S35	0	((non adj conductive) or dielectric or insulat\$4) near5 diffuser and (anode or (counter adj electrode) or counterelectrode) near2 (mesh\$3 or perforat\$4)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/14 17:43
S36	3	((non adj conductive) or dielectric or insulat\$4 or polymer or ceramic) near5 diffuser and (anode or (counter adj electrode) or counterelectrode) near2 (mesh\$3 or perforat\$4)	US-PGPUB; USPAT	OR	ON	2005/10/14 17:47
S37	7	((non adj conductive) or dielectric or insulat\$4 or polymer or ceramic) with diffuser and (anode or (counter adj electrode) or counterelectrode) near2 (mesh\$3 or perforat\$4)	US-PGPUB; USPAT	OR	ON	2005/10/14 17:48
S38	10	((non adj conductive) or dielectric or insulat\$4 or polymer or ceramic) with diffuser and (anode or (counter adj electrode) or counterelectrode or electrode) near2 (mesh\$3 or perforat\$4)	US-PGPUB; USPAT	OR	ON	2005/10/14 17:50
S39	4	((non adj conductive) or dielectric or insulat\$4 or polymer or ceramic) with diffuser and (anode or (counter adj electrode) or counterelectrode or electrode) near2 (mesh\$3 or perforat\$4)	USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/14 17:50
S40	25	((non adj conductive) or dielectric or insulat\$4 or polymer or ceramic) with diffuser and (anode or (counter adj electrode) or counterelectrode or electrode) with (mesh\$3 or perforat\$4)	US-PGPUB; USPAT	OR	ON	2005/10/14 17:54
S41	922	((non adj conductive) or dielectric or insulat\$4 or polymer or ceramic) with diffus\$4 and (anode or (counter adj electrode) or counterelectrode or electrode) with (mesh\$3 or perforat\$4)	US-PGPUB; USPAT	OR	ON	2005/10/14 17:53
S42	256	S41 and (electroplating or (electrochemical adj plating) or plating)	US-PGPUB; USPAT	OR	ON	2005/10/14 17:58
S43	103	((non adj conductive) or dielectric or insulat\$4 or polymer or ceramic) with (baffle or (fluid adj distribut\$4))and (anode or (counter adj electrode) or counterelectrode or electrode) with (mesh\$3 or perforat\$4)	US-PGPUB; USPAT	OR	ON	2005/10/14 17:55

S44	34	S43 and ("204" "205").clas.	US-PGPUB; USPAT	OR	ON	2005/10/14 17:55
S45	89	S42 and ("204" "205").clas.	US-PGPUB; USPAT	OR	ON	2005/10/14 18:00
S46	234	S42 and (wafer or semiconductor or substrate or workpiece)	US-PGPUB; USPAT	OR	ON	2005/10/14 17:58
S48	77	S46 and ("204" "205").clas.	US-PGPUB; USPAT	OR	ON	2005/10/14 18:00
S49	19	(US-20030057098-\$ or US-20030089608-\$ or US-20030178297-\$ or US-20030217916-\$ or US-20020053509-\$ or US-20010050233-\$).did. or (US-5514258-\$ or US-6176995-\$ or US-6254742-\$ or US-6413403-\$ or US-6773571-\$ or US-6261426-\$ or US-4466864-\$ or US-6231743-\$ or US-6500324-\$ or US-6174425-\$ or US-6521102-\$ or US-6503375-\$ or US-6261433-\$).did.	US-PGPUB; USPAT	OR	ON	2005/10/14 18:58
S50	9	S49 and (space or distance or gap) with mm	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/14 18:59